

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Terminals: Solder plated, solderable per MIL-STD-202F method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any
- * Weight: 0.063 gram

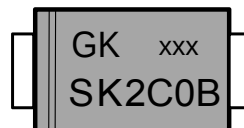


VOLTAGE RANGE

200 Volts

CURRENT

2.0 Ampere



LOGO GK XXX CODE

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	SK2C0B	UNITS
Maximum Recurrent Peak Reverse Voltage	200	V
Maximum RMS Voltage	140	V
Maximum DC Blocking Voltage	200	V
Maximum Average Forward Rectified Current	2.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	50	A
Maximum Instantaneous Forward Voltage at 2.0A	0.92	V
Maximum DC Reverse Current Ta=25°C	0.02	mA
at Rated DC Blocking Voltage Ta=100°C	2	mA
Typical Junction Capacitance (Note1)	170	PF
Typical Thermal Resistance RθJL (Note 2)	12	°C/W
Operating Temperature Range Tj	-65 — +175	°C
Storage Temperature Range Tstg	-65 — +175	°C

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead Vertical PC Board Mounting 0.375"(9.5mm) Lead Length.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

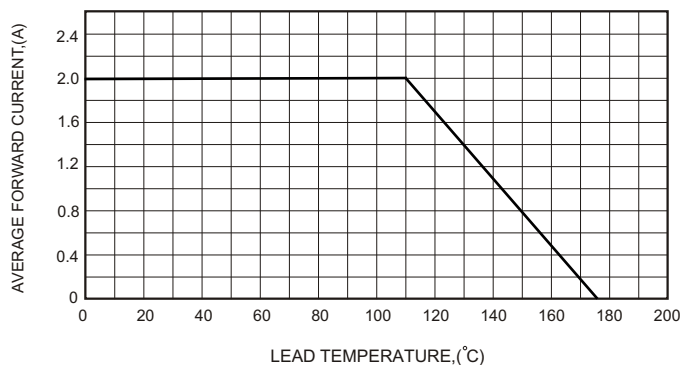


FIG.2-TYPICAL FORWARD CHARACTERISTICS

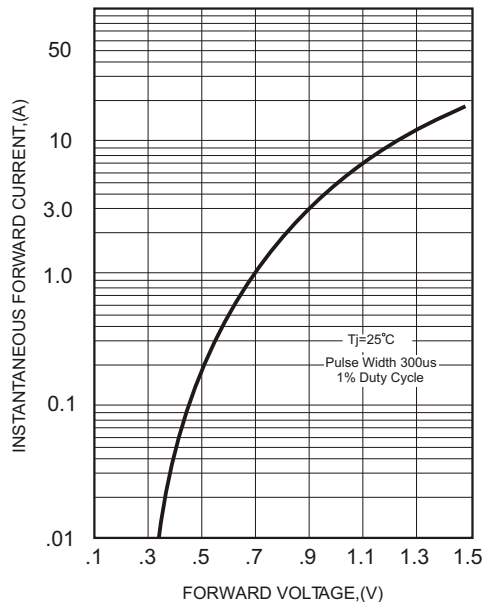


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

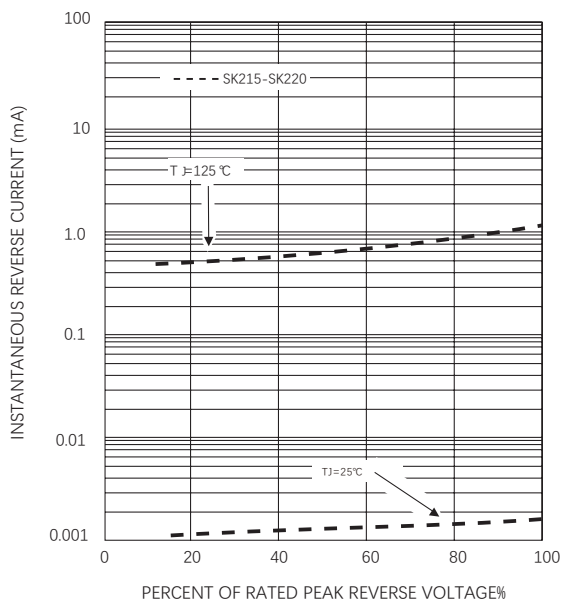


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

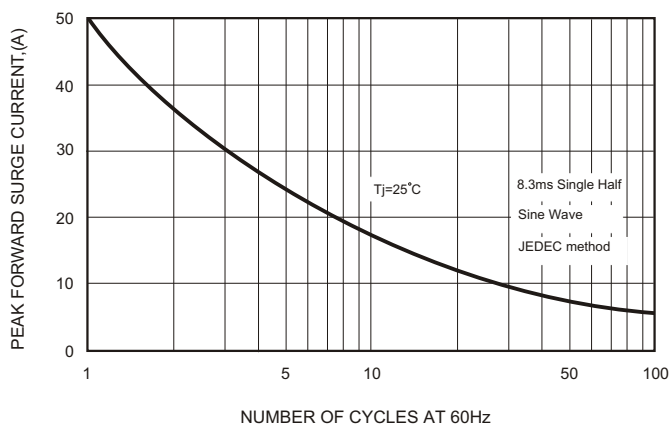
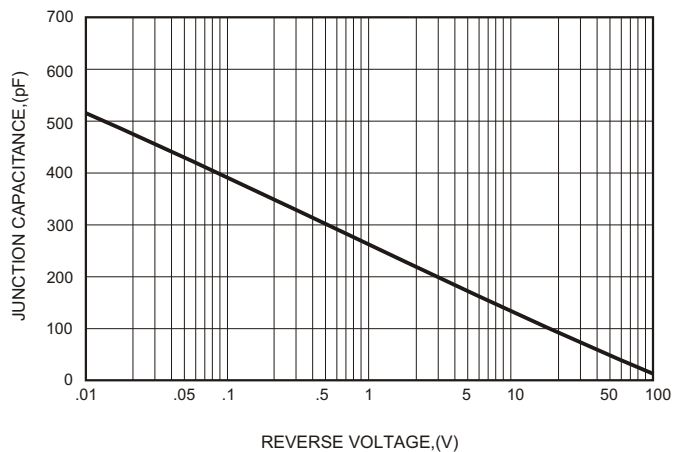


FIG.5-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

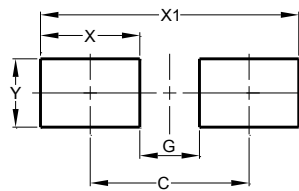
FIG5: Reflow condition

The graph illustrates the reflow condition for a solder joint. The y-axis represents Temperature (°C) and the x-axis represents Time. The curve shows the temperature profile during the reflow process. Key parameters include:

- T_P : Peak temperature.
- T_L : Critical zone temperature (lower limit).
- $T_S(\max)$: Maximum solder temperature.
- $T_S(\min)$: Minimum solder temperature.
- t_s : Preheat time (time from $T_S(\min)$ to T_P).
- t_p : Time at peak temperature.
- t : Total time from the start of preheat to the end of the critical zone.
- Preheat**: The initial ramp-up phase.
- Ramp-**: The ramp-down phase.
- Critical Zone**: The temperature range from T_L to T_P .
- time to peak temperature**: The time from the start of preheat to the peak temperature.

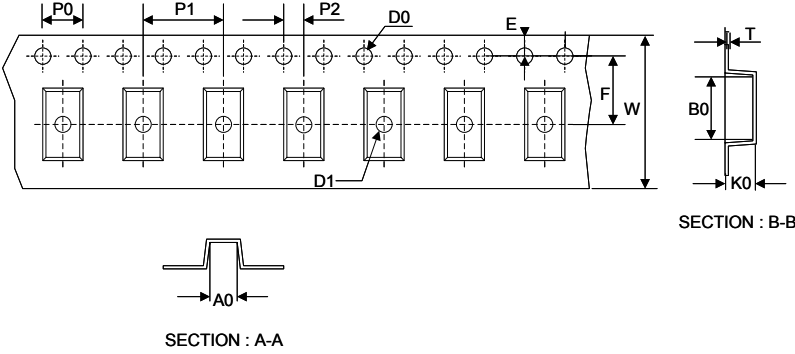
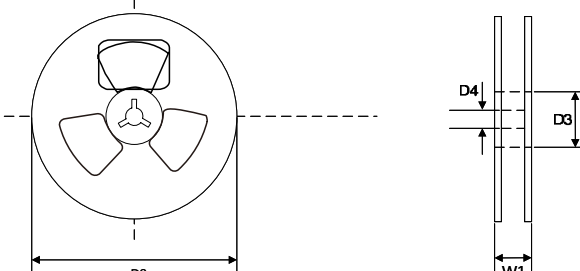
Package Dimensions & Suggested Pad Layout

SMB



Dimensions	Value (in mm)
C	4.70
G	2.20
X	2.50
X1	7.20
Y	2.80

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.60±0.20
		D1	1.60±0.20
		E	1.75±0.20
		F	5.50±0.15
		W	12.00±0.20
		A0	4.00±0.20
		B0	5.45±0.20
		K0	2.50±0.25
		T	0.20±0.10
		D2	330.0±5.0
		D3	73.0Min.
		D4	14.0±2.5
13" Reel		W1	16.0±2.5
		Quantity: 3000PCS	